What is claimed is:

- 1. A printed wiring board comprising:
- a printed wiring substrate having a plurality of a wiring layer, and
- a thermal expansion buffering sheet having a lower coefficient of thermal expansion than that of said printed wiring substrate, which is integrally laminated on a surface of said printed wiring substrate.
- 2. A printed wiring board according to claim 1, wherein 10 a coefficient of thermal expansion of said printed wiring substrate is 13 to 20 ppm, and a coefficient of thermal expansion of said thermal expansion buffering sheet is 6 to 12 ppm.
- 3. A printed wiring board according to claim 1, wherein said printed wiring substrate is a multi-layer wiring board which laminates wiring layers and insulation layers which are made of a glass cloth impregnated with an epoxy resin, alternately.
- 4. A printed wiring board according to claim 1, wherein20 said thermal expansion buffering sheet is made of an aramid.
  - 5. A printed wiring board according to claim 1, wherein an electrode pattern so as to connect a part to be mounted on a surface of said printed wiring board is provided on a surface of said thermal expansion buffering sheet.
- 6. A printed wiring board according to claim 5, wherein said part to be mounted on said surface of said printed wiring board is connected to said electrode pattern via a solder ball.
  - 7. A printed wiring board comprising:

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a multi-layer wiring section which laminates wiring layers and insulation layers alternately,

a thermal expansion buffering sheet having a lower coefficient of thermal expansion than that of said multi-layer wiring section, which is integrally laminated on a surface of said multi-layer wiring section.

8. A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately,

a thermal expansion buffering sheet having a lower coefficient of thermal expansion than that of said multi-layer wiring section, which is integrally laminated on a surface of said multi-layer wiring section, and

an electrode pattern provided on a surface of said thermal expansion buffering sheet so as to connect a part to be mounted on a surface of said printed wiring board.

9. A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately,

a thermal expansion buffering sheet, a material of which is aramid, having a lower coefficient of thermal expansion than that of said multi-layer wiring section, which is integrally laminated on a surface of said multi-layer wiring section.

25 10. A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately,

a thermal expansion buffering sheet, a material of which is aramid, having a lower coefficient of thermal

expansion than that of said multi-layer wiring section, which is integrally laminated on a surface of said multi-layer wiring section, and

an electrode pattern provided on a surface of said thermal expansion buffering sheet so as to connect a part to be mounted on a surface of said printed wiring board.